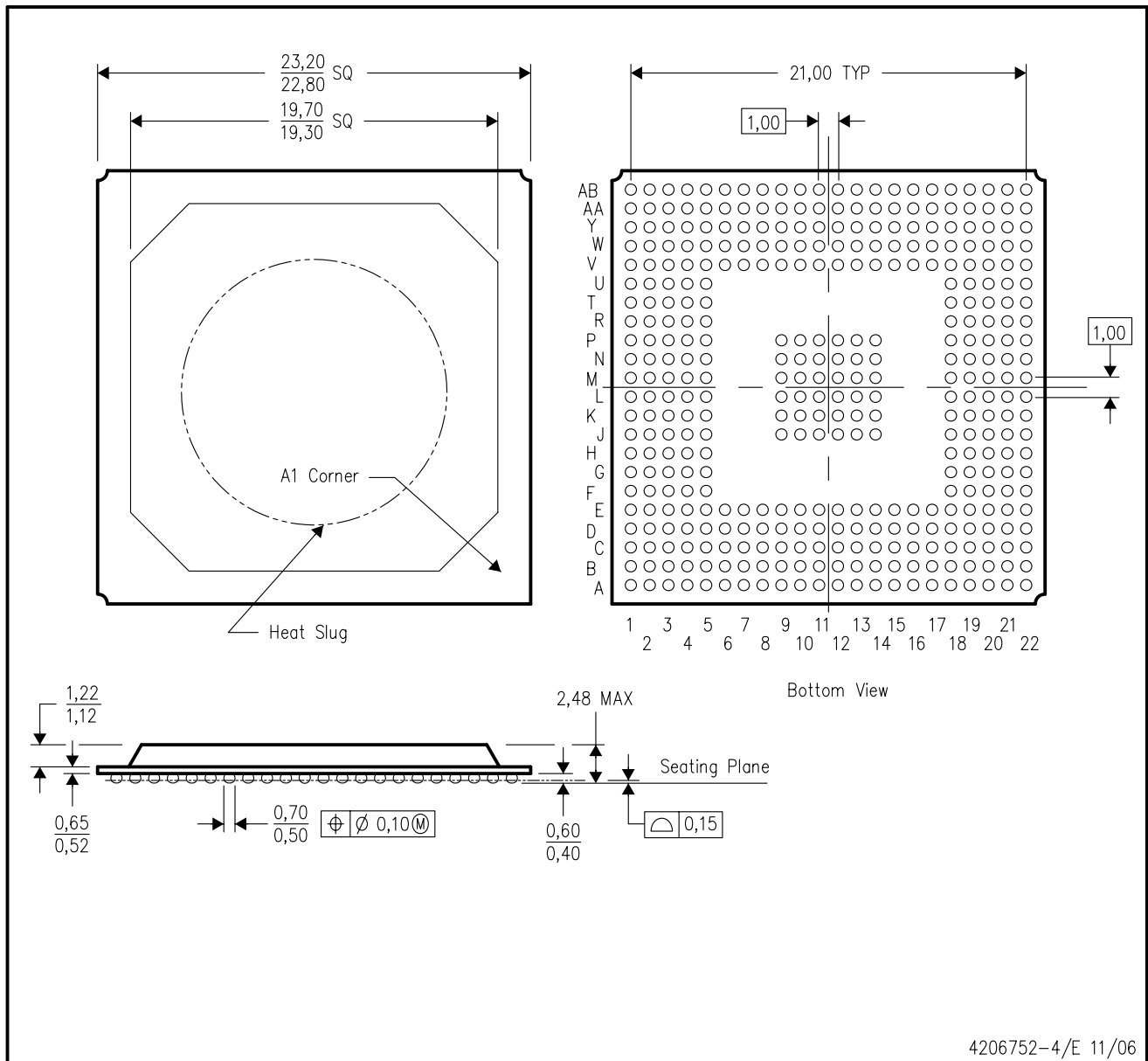


ZDU (S-PBGA-N376)

PLASTIC BALL GRID ARRAY



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Falls within JEDEC MO-151
 - D. Thermally enhanced molded plastic package with heat slug (HSL).
 - E. This is a lead-free solder ball design.

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Post Office Box 655303 Dallas, Texas 75265